Technical Data Sheet

Bondloc BKIT – Mitre Kit Revised 03.08.10



Bondloc BKIT – Mitre Kit

PRODUCT DESCRIPTION

Bondloc Mitre Kit is a fast acting two component system comprising of cyanoacrylate adhesive and activator. It bonds most surfaces within 10 seconds, reducing mitre assembly bonding times compared to conventional wood adhesives.

APPLICATIONS

Bondloc Mitre Kit can be used to bond a variety of materials including MDF, wood, chipboard, rubber, plastics, Perspex, uPVC, ceramics, aluminium and metals.

USEFUL NOTES

Fast acting High viscosity adhesive – low soak in to give better bond strength. Gap filling up to 0.2mm Activator reduces blooming and odour. Easy to use

INSTRUCTIONS FOR USE

Ensure surfaces are clean, dry and free from dust, grease and other contaminants.

Spray one surface with the activator Apply adhesive sparingly to the other surface

Bring together, position and hold for about 10 seconds.

TECHNICAL FEATURES

Base	2 component
	cyanoacrylate
Curing system	Chemical curing
Adhesive	
Appearance	Clear liquid
Specific gravity	1.06 g/cm ³
Viscosity	1200-1800cps
(Brookfield) @	
25°C	
Gap fill	Up to 0.2mm
Working	-120 – 80°C
temperature	
Activator	
Appearance	Clear liquid
Specific gravity	0.79 g/cm ³

STORAGE

Store in original unopened containers between 4 and 25°C. Reseal immediately once used. Protect from sources of ignition.

HEALTH & SAFETY

This technical information sheet does not constitute a Material Safety Data Sheet (MSDS). Before using this product please ensure you have read and full understood Bondloc Mitre Kit MSDS.

PRESENTATION

Kit.....50g/200ml, 100g/400ml